

Benchmark
from T

hp2054

C
rler

... in two
... current
... approximately
... Then a volt-
... completes the

... provides status indica-
... larger states and faults
... determination of the
... and charge-system condi-

BAT	
VCOMP	<input type="checkbox"/> 4
ICOMP	<input type="checkbox"/> 5
ITERM	<input type="checkbox"/> 6
SNS	<input type="checkbox"/> 7
TS	<input type="checkbox"/> 8
	<input type="checkbox"/> 12
	<input type="checkbox"/> 11
	<input type="checkbox"/> 10
	<input type="checkbox"/> 9
	<input type="checkbox"/> LCOM
	<input type="checkbox"/> BTST
	<input type="checkbox"/> TPWM

DSEL

bq2954

Pin Descriptions

TM	Time-out programming input Sets the maximum charge time. The resistor and capacitor values are determined using Equation 5. Figure 10 shows the resistor/capacitor connection.	TPWM	Regulation timebase input Uses an external timing capacitor to ground to set the pulse-width modulation (PWM) frequency. See Equation 7.
CHG	Charge active output An open-drain output is driven low when the battery is removed, during a temperature pend, when a fault condition is present, or when charge is done. CHG can be used to disable a high-value load capacitor to detect quickly any battery removal.	BTST	Battery test output Driven high in the absence of a battery in order to provide a potential at the battery terminal when no battery is present.
BAT	Battery voltage input Sense input. This potential is generally developed using a high-impedance resistor divider network connected between the positive and the negative terminals of the battery. See Figures 6 and 7 and Equation 1.	LCOM	Common LED output Common output for LED ₁₋₂ . This output is in a high-impedance state during initialization to read programming input on DSEL and CSEL.
VCOMP	Voltage loop compensation input Connects to an external R-C network to stabilize the regulated voltage.	VSS	Ground
ICOMP	Current loop compensation input Connects to an external R-C network to stabilize the regulated current.	VCC	VCC supply 5.0V, ±10%
ITERM	Charge full and minimum current termination select Three-state input is used to set I _{FULL} and I _{MIN} for fast charge termination. See Table 4.	MOD	Current-switching control output Pulse-width modulated push/pull output used to control the charging current to the battery. MOD switches high to enable current flow and low to inhibit current flow. (The maximum duty cycle is 80%.)
SNS	Charging current sense input Battery current is sensed via the voltage developed on this pin by an external sense-resistor.	LED₁-LED₂	Charger display status 1-2 outputs Drivers for the direct drive of the LED display. These outputs are tri-stated during initialization so that DSEL and CSEL can be read.
TS	Temperature sense input Used to monitor battery temperature. An external resistor-divider network sets the lower and upper temperature thresholds. (See Figures 8 and 9 and Equations 3 and 4.)	DSEL	Display select input (shared pin with LED₂) Three-level input that controls the LED ₁₋₂ charge display modes.
		CSEL	Charge sense-select input (shared pin with LED₁) Input that controls whether current is sensed on low side of battery or high side of battery. A current mirror is required for high-side sense.

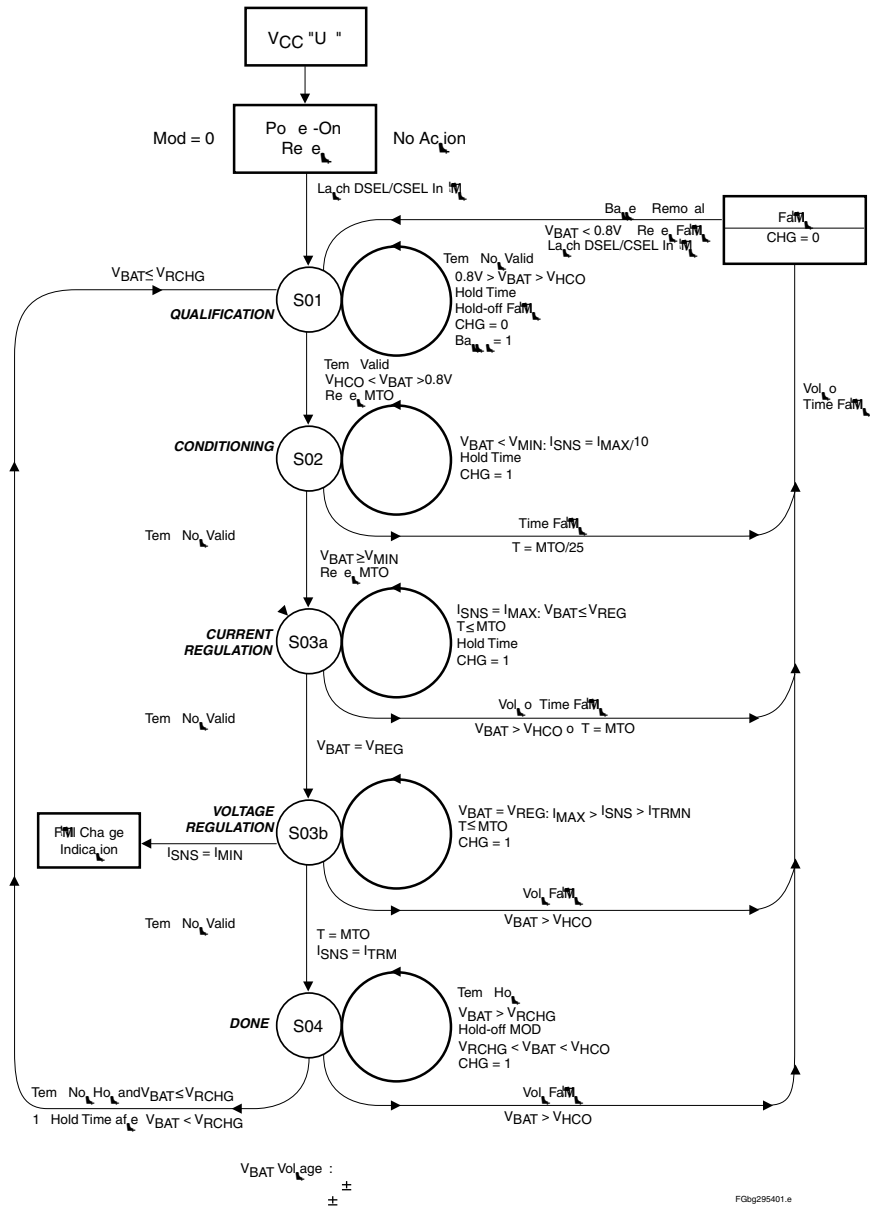
Functional Description

The bq2954 functional operation is described in terms of the following (Figure 1):

- Charge algorithm
- Charge qualification
- Charge status display
- Configuring the display and termination
- Voltage and current monitoring
- Battery insertion and removal
- Temperature monitoring
- Maximum time-out
- Charge regulation
- Recharge after fast charge

Charge Algorithm

The bq2954 uses a two-phase fast-charge algorithm. In



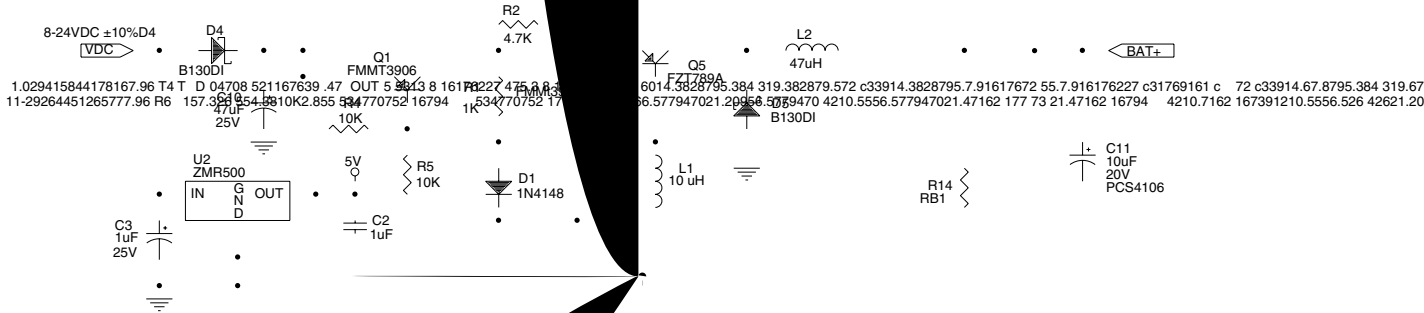
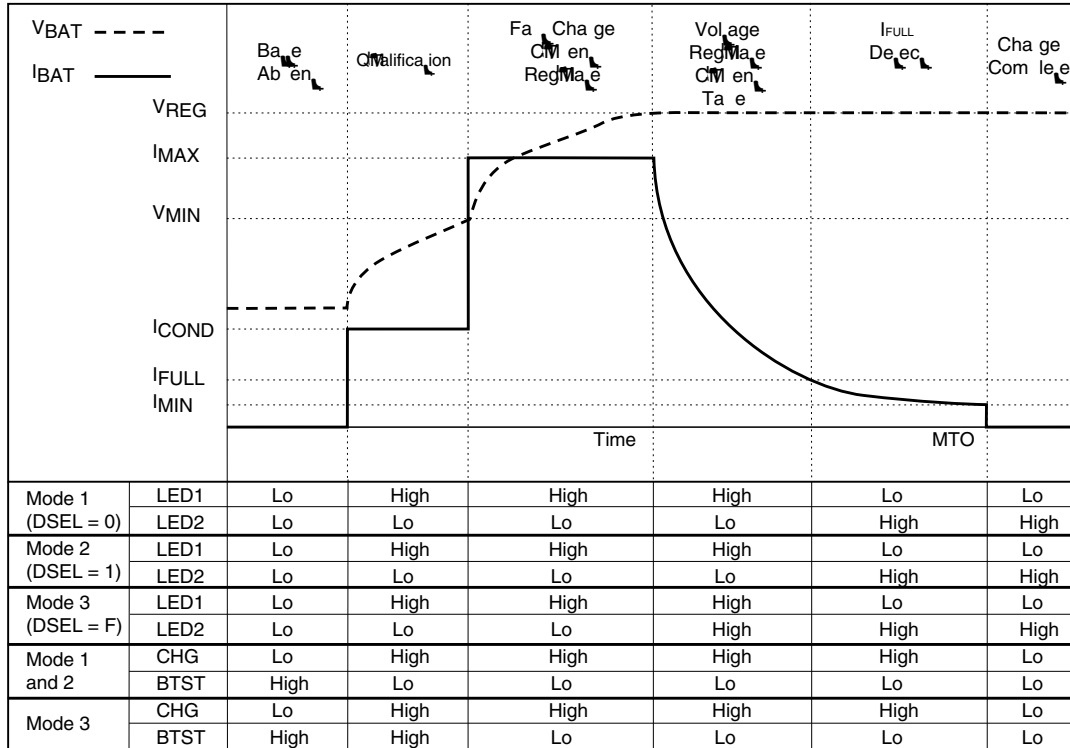


Table 1. Normal Fast Charge Cycle



GR295401.e

time-out limit t_{QT} (i.e., the battery has failed short), the bq2954 enters the Fault state. Then t_{QT} is set to 25% of t_{MTO} . If V_{MIN} is achieved before expiration of the time limit, the bq2954 begins fast charging.

Once in the Fault state, the bq2954 waits until V_{CC} is cycled or a new battery insertion is detected. It then starts a new charge cycle and begins the qualification process again.

Charge Status Display

Charge status is indicated by the LED driver outputs LED₁–LED₂. Three display modes (Tables 1– 3) are available in the bq2954 and are selected by configuring pin DSEL. Table 1 illustrates a normal fast charge cycle, Table 2 a recharge-after-fast-charge cycle, and Table 3 an abnormal condition.

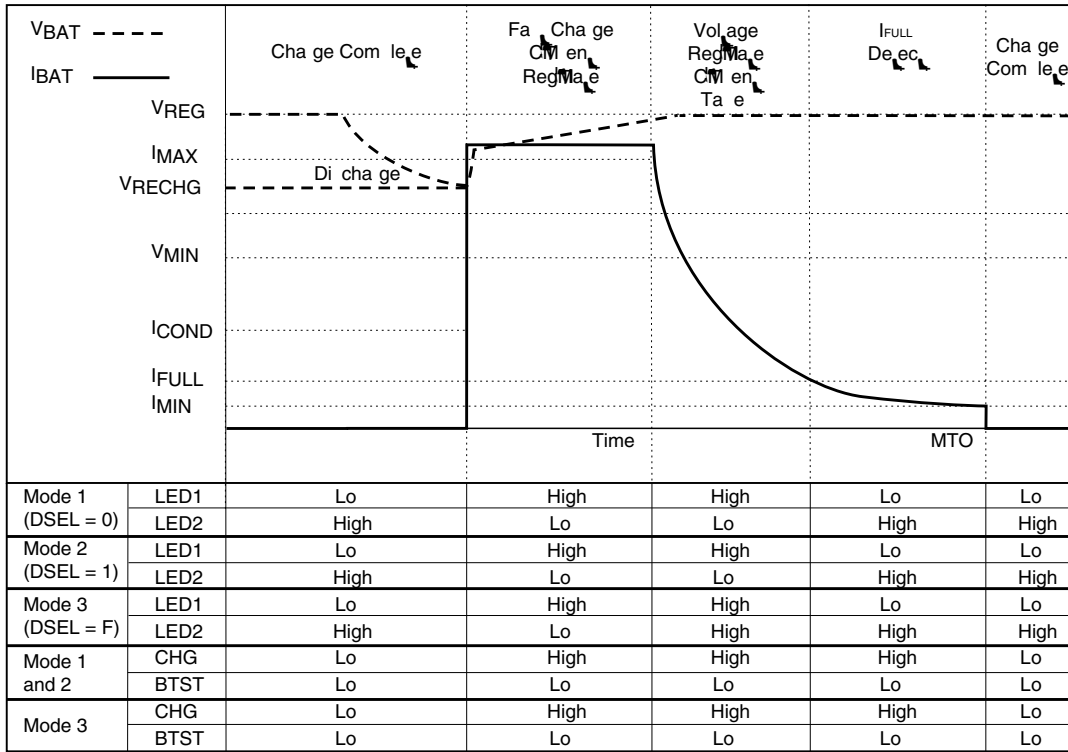
Configuring the Display Mode, I_{FULL}/I_{MIN} , and I_{SENSE}

DSEL/LED₂ and CSEL/LED₁ are bi-directional pins with two functions: as LED driver pins (output) and as programming pins (input). The selection of pull-up, pull-down, or no-resistor programs the display mode on DSEL as shown in Tables 1 through 3. A pull-down or no-resistor programs the current-sense mode on CSEL.

The bq2954 latches the programming data sensed on the DSEL and CSEL input when V_{CC} rises to a valid level. The LEDs go blank for approximately 400ms (typical) while new programming data are latched.

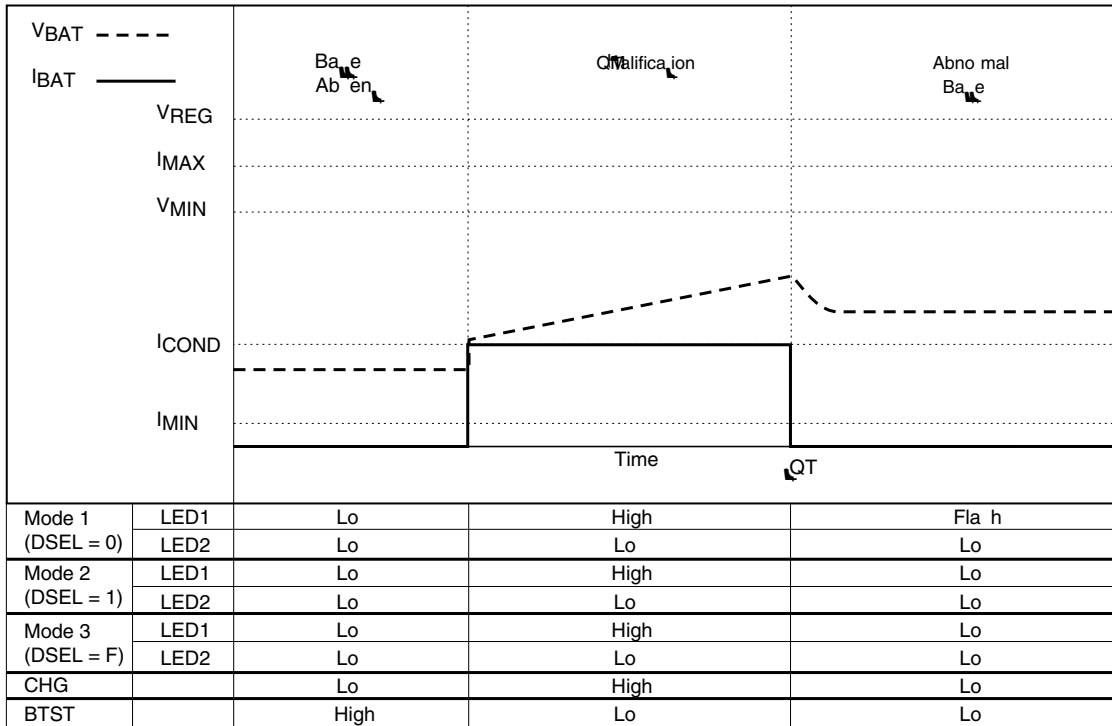
When fast charge reaches a condition where the charging current drops below I_{FULL} , the LED₁ and LED₂ outputs indicate a full-battery condition. Fast charge terminates when the charging current drops below the

Table 2. Recharge After Fast Charge Cycle



G b 295402.e

Table 3. Abnormal Condition



GR295403.e

Table 4. I_{FULL} and I_{MIN} Thresholds

ITERM	I _{FULL}	I _{MIN}
0	I _{MAX} /5	I _{MAX} /10
1	I _{MAX} /10	I _{MAX} /15
Z	I _{MAX} /15	I _{MAX} /20

minimum current threshold, I_{MIN} . The I_{FULL} and I_{MIN} thresholds are programmed using the I_{TERM} input pin (See Table 4.)

Figures 4 and 5 show the bq2954 configured for display mode 2 and $I_{FULL} = I_{MAX}/5$ while $I_{MIN} = I_{MAX}/10$.

Voltage and Current Monitoring

In low-side current sensing, the bq2954 monitors the battery pack voltage as a differential voltage between BAT and pins. In high-side current sensing, the bq2954 monitors the battery pack voltage as a differential voltage between BAT and V_{SS} pins. This voltage is derived by scaling the battery voltage with a voltage divider. (See Figures 6 and 7.) The resistance of the voltage divider must be high enough to minimize battery drain but low enough to minimize noise susceptibility. $RB1 + RB2$ is typically between 150k Ω and 1M Ω . The voltage-divider resistors are calculated from the following:

$$\frac{RB1}{RB2} = \frac{N * V_{CELL}}{V_{REG}} - 1 \quad (1)$$

where

V_{CELL} = Manufacturer-specified charging cell voltage
 N = Number of cells in series
 $V_{REG} = 2.05V$

The current sense resistor, R_{SNS} (see Figures 6 and 7), determines the fast-charge current. The value of R_{SNS} is given by the following:

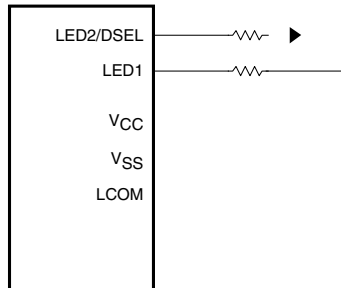
$$R_{SNS} = \frac{0.25V}{I_{MAX}} \quad (2)$$

where I_{MAX} is the current during the constant-current phase of the charge cycle. (See Table 1.)

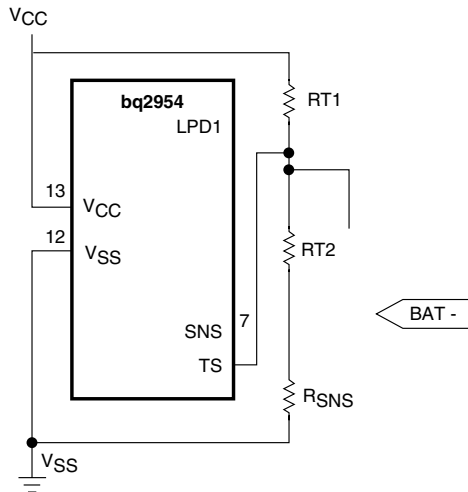
Battery Insertion and Removal

V_{BAT} is interpreted by the bq2954 to detect the presence or absence of a battery. The bq2954 determines that a battery is present when V_{BAT} is between the High-Voltage Cutoff ($V_{HCO} = V_{REG} + 0.25V$) and the Low-Voltage Cutoff ($V_{LCO} = 0.8V$). When V_{BAT} is outside this range, the bq2954 determines that no battery is present and transitions to the battery test state, testing for valid battery voltage. The bq2954 detects battery removal when V_{BAT} falls below V_{LCO} . The BTST pin is driven high during battery test and can activate an exter-

bq2954



Fgb_295402LS.e



FGb 295404LS.e

Disabling Temperature Sensing

Temperature sensing can be disabled by placing a 10kΩ resistor between TS and BAT- and a 10kΩ resistor between TS and VCC. See Figures 8 and 9.

Maximum Time-Out

Maximum Time-Out period (t_{MTO}) is programmed from 1 to 24 hours by an R-C network on the TM pin (see Figure 10) per the following equation:

$$t_{MTO} = 500 * R * C \tag{5}$$

where R is in ohms, C is in Farads, and t_{MTO} is in hours. The recommended value for C is 0.1μF.

The MTO timer is reset at the beginning of fast charge. If the MTO timer expires during the voltage regulation phase, fast charging terminates and the bq2954 enters the Charge Complete state. If the conditioning phase continues for time equal to t_{QT} (MTO/4) and the battery potential does not reach V_{MIN} , the bq2954 enters the fault state and terminates charge. See Table 3. If the MTO timer expires during the current-regulation phase (V_{BAT} never reaches V_{REG}), fast charging is terminated, and the bq2954 enters the fault state.

Charge Regulation

The bq2954 controls charging through pulse-width modulation of the MOD output pin, supporting both constant-current and constant-voltage regulation. Charge current is monitored at the SNS pin, and charge voltage is monitored at the BAT pin. These voltages are compared to an internal reference, and the MOD output is modulated to maintain the desired value. The maximum duty cycle is 80% .

Voltage at the SNS pin is determined by the value of resistor R_{SNS} , so nominal regulated current is set by the following equation:

$$I_{MAX} = V_{SNS} / R_{SNS} \quad (6)$$

The switching frequency of the MOD output is determined by an external capacitor (C_{PWM}) between the pin TPWM and VSS pins, per the following:

$$f_{PWM} = \frac{1 * 10^{-4}}{C_{PWM}} \quad (7)$$

Where C is in Farads and the frequency is in Hz. A typical switching rate is 100kHz, implying $C_{PWM} = 0.001\mu F$. MOD pulse width is modulated between 0 and 80% of the switching period.

Absolute Maximum Ratings

Symbol	Parameter	Minimum	Maximum	Unit	Notes
V _{CC}	V _{CC} relative to V _{SS}	-0.3	+7.0	V	
V _T	DC voltage applied on any pin excluding V _{CC} relative to V _{SS}	-0.3	+7.0	V	
T _{OPR}	Operating ambient temperature	-20	+70	°C	Commercial
		-40	+85	°C	Industrial "N"
T _{STG}	Storage temperature	-55	+125	°C	
T _{SOLDER}	Soldering temperature	-	+260	°C	10s max.

Note: Permanent device damage may occur if **Absolute Maximum Ratings** are exceeded. Functional operation should be limited to the Recommended DC Operating Conditions detailed in this data sheet. Exposure to conditions beyond the operational limits for extended periods of time may affect device reliability.

DC Thresholds (T_A = T_{OPR}; V_{CC} = 5V ± 10%)

Symbol	Parameter	Rating	Unit	Tolerance	Notes
V _{REG}	Internal reference voltage	2.05	V	1%	TA = 25°C
	Temperature coefficient	-0.5	mV/°C	10%	
V _{LTF}	TS maximum threshold	0.6 * V _{CC}	V	±0.03V	Low-temperature fault
V _{HTF}	TS hysteresis threshold	0.44 * V _{CC}	V	±0.03V	High-temperature fault
V _{TCO}	TS minimum threshold	0.4 * V _{CC}	V	±0.03V	Temperature cutoff
V _{HCO}	High cutoff voltage	V _{REG} + 0.25V	V	±0.03V	
V _{MIN}	Under-voltage threshold at BAT	1.5	V	±0.05V	
V _{RECHG}	Recharge voltage threshold at BAT	1.92	V	±0.05V	
V _{LCO}	Low cutoff voltage	0.8	V	±0.03V	
V _{SNS}	Current sense at SNS	0.250	V	10%	I _{MAX}
		0.025	V	10%	I _{COND}

bq2954

Recommended DC Operating Conditions (T_A = T_{OPR})

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
V _{CC}	Supply voltage	4.5	5.0	5.5	V	
V _{TEMP}	TS voltage potential	0	-	V _{CC}	V	V _{TS} - V _{SNS}
V _{BAT}	BAT voltage potential	0	-	V _{CC}	V	
I _{CC}	Supply current	-	2	4	mA	Outputs unloaded
	DSEL tri-state open detection	-2	-	2	μA	Note
I _{IZ}	I _{TERM} tri-state open detection	-2	-	2	μA	
V _{IH}	Logic input high	V _{CC} - 0.3	-	-	V	DSEL, I _{TERM}
V _{IL}	Logic input low	-	-	V _{SS} + 0.3	V	DSEL, CSEL, I _{TERM}
	LED ₁ , LED ₂ , BTST, output high	V _{CC} - 0.8	-	-	V	I _{OH} ≤ 10mA
V _{OH}	MOD output high	V _{CC} - 0.8	-	-	V	I _{OH} ≤ 10mA
	LED ₁ , LED ₂ , BTST, output low	-	-	V _{SS} + 0.8	V	I _{OL} ≤ 10mA
	MOD output low	-	-	V _{SS} + 0.8	V	I _{OL} ≤ 10mA
V _{OL}	CHG output low	-	-	V _{SS} + 0.8	V	I _{OL} ≤ 5mA, Note 3
	LCOM output low	-	-	V _{SS} + 0.5	V	I _{OL} ≤ 30mA
	LED ₁ , LED ₂ , BTST, source	-10	-	-	mA	V _{OH} = V _{CC} - 0.5V
I _{OH}	MOD source	-5.0	-	-	mA	V _{OH} = V _{CC} - 0.5V
	LED ₁ , LED ₂ , BTST, sink	10	-	-	mA	V _{OL} = V _{SS} + 0.5V
	MOD sink	5	-	-	mA	V _{OL} = V _{SS} + 0.8V
I _{OL}	CHG sink	5	-	-	mA	V _{OL} = V _{SS} + 0.8V, Note 3
	LCOM sink	30	-	-	mA	V _{OL} = V _{SS} + 0.5V
	DSEL logic input low source	-	-	+30	μA	V = V _{SS} to V _{SS} + 0.3V, Note 2
I _{IL}	I _{TERM} logic input low source	-	-	+70	μA	V = V _{SS} to V _{SS} + 0.3V, Note 2

Impedance ($T_A = T_{OPR}$; $V_{CC} = 5V \pm 10\%$)

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
R _{BATZ}	BAT pin input impedance	50	-	-	MΩ	
R _{SNSZ}	SNS pin input impedance	50	-	-	MΩ	
R _{TSZ}	TS pin input impedance	50	-	-	MΩ	
R _{PROG1}	Soft-programmed pull-up or pull-down resistor value (for programming)	-	-	10	kΩ	DSEL, CSEL
R _{PROG2}	Pull-up or pull-down resistor value	-	-	3	kΩ	ITERM
R _{MTO}	Charge timer resistor	20	-	480	kΩ	

Timing ($T_A = T_{OPR}$; $V_{CC} = 5V \pm 10\%$)

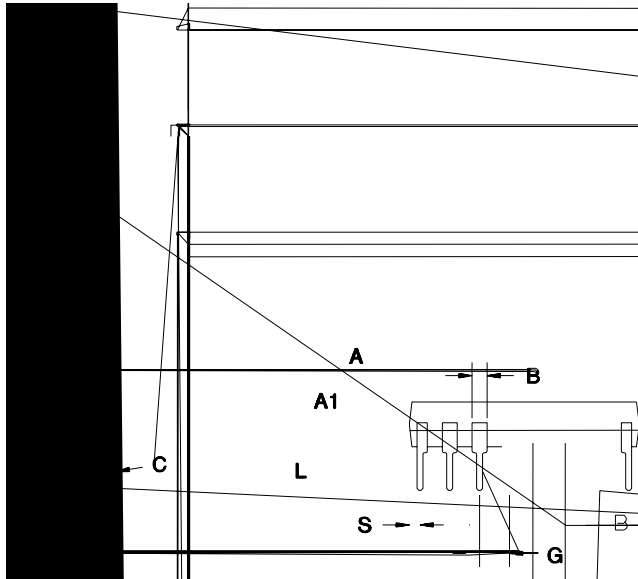
Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
t _{MTO}	Charge time-out range	1	-	24	hours	See Figure 10
t _{QT}	Pre-charge qual test time-out period	-	0.25 * t _{MTO}	-	-	
t _{HO}	Pre-charge qual test hold-off period	300	600	900	ms	
f _{PWM}	PWM regulator frequency range	-	100	200	kHz	See Equation 7
d _{PWM}	Duty cycle	0	-	80	%	

Capacitance

Symbol	Parameter	Minimum	Typical	Maximum	Unit
C _{MTO}	Charge timer capacitor	-	-	0.1	μF
C _{PWM}	PWM capacitor	-	0.001	-	μF

bq2954

16-Pin DIP Narrow (PN)



16-Pin PN (0.300" DIP)

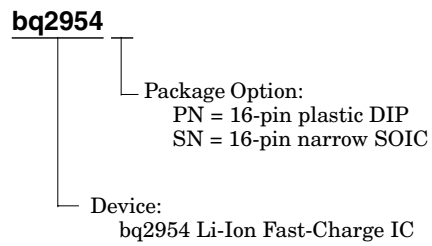
Dimension	Inches		Millimeters	
	Min.	Max.	Min.	Max.
A	0.160	0.180	4.06	4.57
A1	0.015	0.040	0.38	1.02
B	0.015	0.022	0.38	0.56
B1	0.055	0.065	1.40	1.65
C	0.008	0.013	0.20	0.33
D	0.740	0.770	18.80	19.56
E	0.300	0.325	7.62	8.26
E1	0.230	0.280	5.84	7.11
e	0.300	0.370	7.62	9.40
G	0.090	0.110	2.29	2.79
L	0.115	0.150	2.92	3.81
S	0.020	0.040	0.51	1.02

Data Sheet Revision History

Change No.	Page No.	Description of Change
1	All	“Final” changes from “Preliminary” version

Note: Change 1 = Oct. 1998 B changes from Nov. 1997 “Preliminary.”

Ordering Information



IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH,

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
BQ2954PN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	2954PN-A3	Samples
BQ2954PNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	2954PN-A3	Samples
BQ2954SN	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2954 (-A3 ~ A3)	Samples
BQ2954SNG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2954 (-A3 ~ A3)	Samples
BQ2954SNTR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2954 (-A3 ~ A3)	Samples
BQ2954SNTRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2954 (-A3 ~ A3)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.



www.ti.com

PACKAGE OPTION ADDENDUM

11-Apr-2013

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

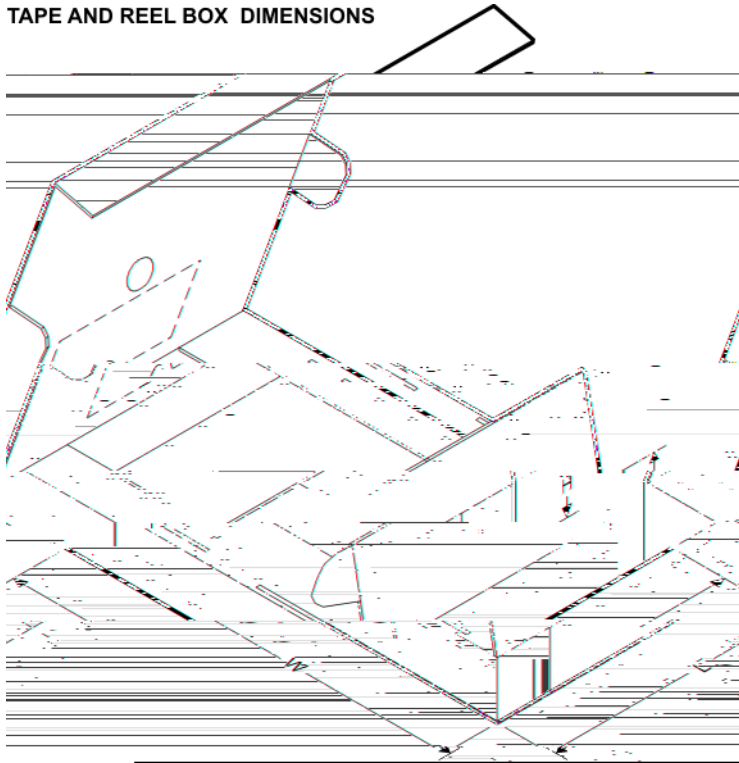
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ2954SNTR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ2954SNTR	SOIC	D	16	2500	367.0	367.0	38.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to